



FOR MESSRS:

ON DATE OF:

APPROVED BY:

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History of Version

Version	Contents	Date	Note
01	NEW VERSION	2019/11/4	SPEC.
	BOLI		

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1. Numbering System

В	L	25664	В	-	W	R	Ν	Ν	н	Ν	\$	
0	1	2	3		4	5	6	7	8	9	10	11

0	Bolymin	В				
		С	Character	type	Р	TAB /TCP type
	F	COF type			Color STN	
1	Module Type	G	Graphic typ	be	L	OLED
		0	COG type		Z	Customize
	- /		2004	20 character type,4	lines	
2	Format		12232	122 × 32 dots		
3	Version No.	В			_	
		В	STN / Blue	, OLED/Blue	н	HTN
		С	Color	Color FSTN		TN
		F	FSTN			STN/Yellow-green
		G	STN/Grey		D	OLED/Blue+Yellow
4	LCD Color	Color A OLED/Blue+Yellow+Green		+Yellow+Green	Е	OLED/Yellow
			OLED/Green		R	OLED/RED
		W OLED/White		te	J	ASTN
		К	DFSTN	DFSTN		VA LCD
		R	Positive/ref	flective	М	Positive/ transmissive
5	LCD Type	Р	Positive/tra	insflective	N	Negative/ transmissive
		Т	Negative/ t	ransflective		
		L	(LED)Array/y	ellow-green	G	(LED)Edge/yellow-green
		М	(LED)Array/a		Н	(LED)Edge/white
		R	(LED)Array/re		D	(LED)Edge/blue
	Backlicht	U	(LED)Array/b		E B	(EL)white
6	Backlight type/color	W		(LED)Array/white		
	1990,00101	С	(CCFL) white		F	(LED)Array/RGB
		Y	(LED)Array/y		N	No backlight
		0	(LED)Array/o		K	(LED)Edge/green
		А	(LED)Edge/a		Q	(LED)Edge/red
		J	(LED)Array/g	reen		(LED)Edge/RGB

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				1	
			(LED) arrayred/green	Р	(LED)Edge/orange
		S	(LED)edge/RGW	Т	(LED)edge red/green
		V	EL blue/green [、]	Х	(LED) Edgewhite /red
		J	English/Japanese Font	С	English/Cyrillic Font
		G	Chinese(simple)	н	English/Hebrew Font
		Е	English/European Font (ST7066U0B-BB)	S	English/European Font (ST7066U-0E-BB)
7	CGRAM Font	F	Chinese(traditional)	М	Japanese-Kanji
		Z	Z=Chinese(simple)+Chinese (traditional)+Japanese+Korean	к	Korean (only for BG16032A BG24064C)
		А	English/Arabic Font	D	Chinese (simple/traditional) English/Japanese
		В	English/Japanese/European	N	None
		В	Bottom/Normal Temperature06:00	W	Top/Wide Temperature 12:00
		Н	Bottom/Wide Temperature 06:00	Е	Top/Ultra Temperature 12:00
	View Angle /Operation	С	9H/Normal Temperature 09:00	U	Bottom/Ultra wide Temperature 06:00
8	Temperature	Т	Top/Normal Temperature 12:00	F	9H/Ultra wide Temperature 09:00
		G	3H/Wide Temperature 3:00	D	9H/Wide Temperature 09:00
		I	3H/ Ultra Wide Temperature 3:00		
9	Special Code	N	Positive voltage for LCD	Т	Negative voltage and Temperature compensation for LCD
		Ρ	Touch panel	3/5	3/5 voltage logic power supply
10	RoHS	\$			
11	Customer Code	<u>00</u> 0	$\sim \underline{99} 0 \rightarrow \underline{AA} 0 \sim \underline{ZZ} 0$		



2. General Specification

(1) Mechanical Dimension

Item	Standard Value	Unit
Number of dots	256x64	dots
Module dimension (L*W*H)	87.4*64.5*2.01	mm
Active area	79.084*19.756	mm
Dot size	0.289(W)×0.289(H)	mm
Dot pitch	0.309(W)×0.309 (H)	mm
Color	White	

(2) Controller IC: SSD1322 Controller

(3) Temperature Range

Operating	BO	-40 ~ +70°C	
Storage		-40 ~ +85°C	

3. Absolute Maximum Ratings

Item	Symbol	Condition	Min	Тур	Max	Unit
Operating Temperature	Тор		-40	_	+85	°C
Storage Temperature	TST		-40	_	+85	°C
Humidity					85	%
Supply Voltage For Logic	VDD		2.4	_	3.5	V
Supply Voltage For Panel	VCC		10		20	
Operating lift time		80cd/m ² , 50% checkerboard	13000(1)			Hrs
Operating lift time		70cd/m ² , 50% checkerboard	16000(2)			Hrs
Operating lift time		60cd/m ² , 50% checkerboard	19000(3)			Hrs

(A) Under VCC = 14V, Ta = $25^{\circ}C$, 50% RH.

(B) Life time is defined the amount of time when the luminance has decayed to

less than 50% of the initial measured luminance.

(1) Setting of 80 cd/m ² :	Contrast setting : 0x70	Frame rate : 105Hz	Duty setting: 1/64
(2) Setting of 70 cd/m^2 :	Contrast setting : 0x5a	Frame rate : 105Hz	Duty setting: 1/64
(3) Setting of 60 cd/m ² :	Contrast setting : 0x49	Frame rate : 105Hz	Duty setting: 1/64



4. Electrical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	V _{DD} -V _{SS}	_	2.4	3.3	3.5	V
Supply Voltage For Panel	Vcc-V _{SS}	_	13.5	14	14.5	V
Input High Vol	V _{IH}	_	$0.8V_{DD}$	_	V _{DD}	V
Input Low Vol	V _{IL}		0	_	$0.2V_{DD}$	V
Output High Vol	V _{OH}	_	$0.9V_{DD}$	_	V _{DD}	V
Output Low Vol.	V _{OL}		0	_	$0.1 V_{DD}$	V
Supply Current For Logic						
(with built-in positive voltage)	I _{DD}	_	_	270	_	mA

5. Optical Characteristics

Item	Min.	Тур.	Max.	Unit	
View Angle	160			deg	
Dark Room contrast	2000:1	-	_	_	
Response Time		10		us	

6. Interface Pin Function

Pin No.	Symbol	Level	Description
1	Vss	0V	Ground
2	Vdd	3.3V	Supply voltage for logic
3	CS	H/L	Chip select pin
4	/RES	H/L	Hardware Reset pin
5	D/C	H/L	H: Data; L: Command.
6	WR	H/L	write signal pin
7	RD	H/L	Read signal pin
8	DB0	H/L	Data bus line
9	DB1	H/L	Data bus line
10	DB2	H/L	Data bus line
11	DB3	H/L	Data bus line
12	DB4	H/L	Data bus line
13	DB5	H/L	Data bus line
14	DB6	H/L	Data bus line
15	DB7	H/L	Data bus line
16	DISF VCC	H/L H	DISF: VCC Voltage ON/OFF VCC: Supply Voltage For OLED

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Default: Parallel 8-Bit 8080 Interface 68j : Parallel 8-Bit 6800 Interface Special Code 20i : SPI Interface Special Code

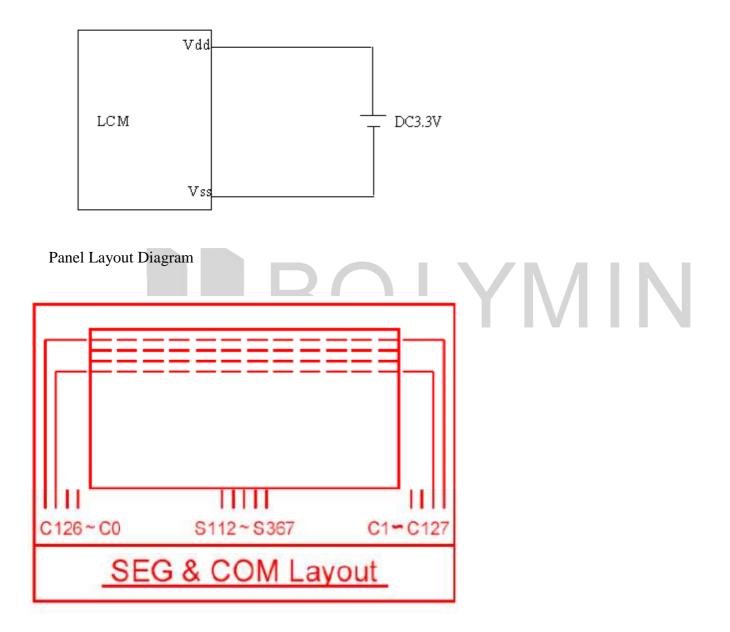
20i : SPI Interface Special Code

MCU interface assignment under different bus interfa	ice mode
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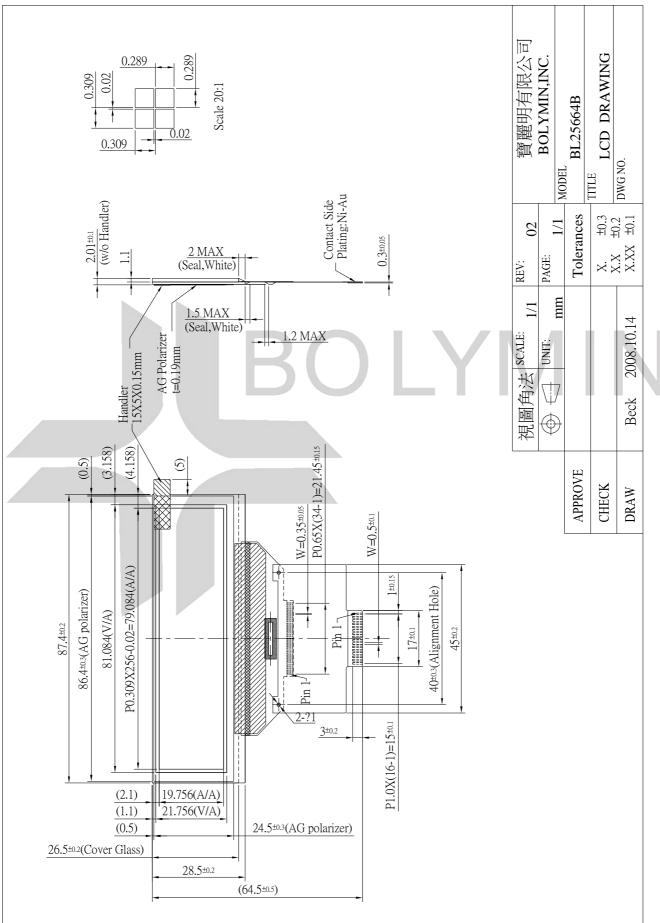
Pin Name Bus	Data/C	Data/Command Interface								Control Signal						
Interface	D 7	D7 D6 D5 D4 D3 D2 D1 D0								R/W #	CS#	D /C#	RES#			
8-bit 8080		•		D[7:0]		•		RD#	WR#	CS#	D/C#	RES#			
8-bit 6800				D[7:0]				Е	R/W#	CS#	D/C#	RES#			
3-wire SPI	Tie LO	W				NC	SDIN	SCLK	Tie L	OW	CS#	Tie LOW	RES#			
4-wire SPI	Tie LO	W				NC	SDIN	SCLK	Tie L	.OW	CS#	D/C#	RES#			



OLED Module operating on "DC 3.3V " input with built-in positive voltage



8. Drawing



BL25664B-WRNNHN\$ VER.01

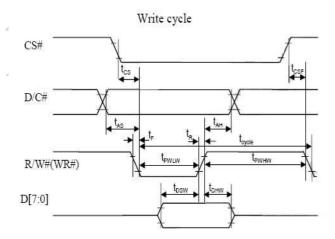


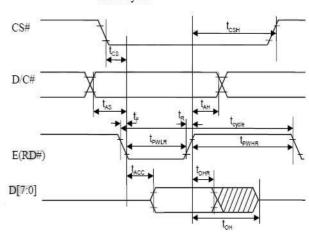
9. SSD1322 controller data 9.1 Timing Characteristics .8080 MPU Interface

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	300	-	-	ns
t _{AS}	Address Setup Time	10	-	-	ns
t _{AH}	Address Hold Time	0	-	-	ns
t _{DSW}	Write Data Setup Time	40	-	-	ns
t _{DHW}	Write Data Hold Time	7	-	-	ns
t _{DHR}	Read Data Hold Time	20	-	-	ns
t _{OH}	Output Disable Time	-	-	70	ns
t _{ACC}	Access Time	-	-	140	ns
t _{PWLR}	Read Low Time	150	-	-	ns
t _{PWLW}	Write Low Time	60	-	-	ns
t _{PWHR}	Read High Time	60	-	-	ns
t _{PWHW}	Write High Time	60	-	-	ns
t _R	Rise Time	-	-	15	ns
t _F	Fall Time	-	-	15	ns
t _{cs}	Chip select setup time	0	-	-	ns
t _{CSH}	Chip select hold time to read signal	0	-	-	ns
t _{CSF}	Chip select hold time	20	-	-	ns

$(V_{DD} - V_{SS} = 2.4 \text{ to } 2.6 \text{V}, V_{DDIO} = 1.6 \text{V}, V_{CI} = 3.3 \text{V}, T_A = 25^{\circ}\text{C})$

8080-series MCU parallel interface characteristics





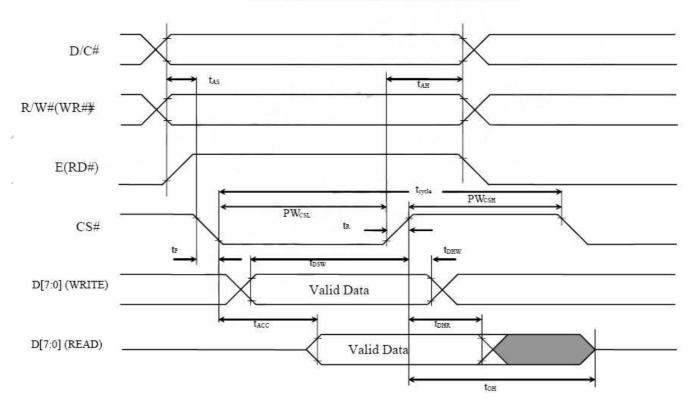
Read cycle



6800 MPU Interface

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	300	-	-	ns
t _{AS}	Address Setup Time	10	-	-	ns
t _{AH}	Address Hold Time	0	-	-	ns
t _{DSW}	Write Data Setup Time	40	-	-	ns
t _{DHW}	Write Data Hold Time	7	-	-	ns
t _{DHR}	Read Data Hold Time	20	-	-	ns
t _{OH}	Output Disable Time	-	-	70	ns
t _{ACC}	Access Time	-	-	140	ns
PW _{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW _{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t _R	Rise Time	-	-	15	ns
t _F	Fall Time	- /	-	15	ns

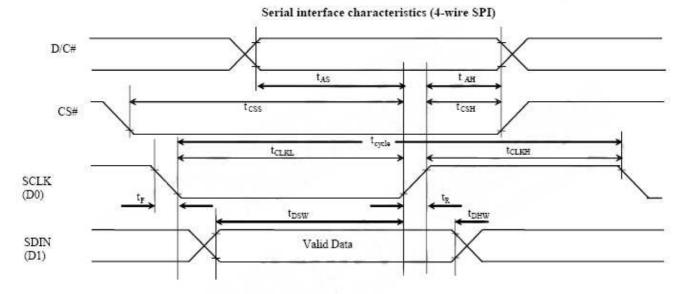
6800-series MCU parallel interface characteristics

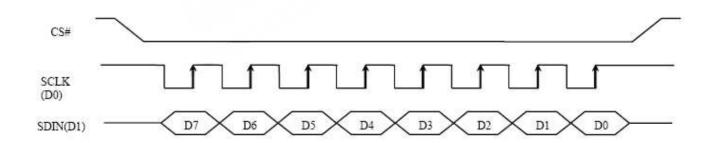


Serial Interface(4-wire SPI)

 $(V_{DD} - V_{SS} = 2.4 \text{ to } 2.6 \text{V}, V_{DDIO} = 1.6 \text{V}, V_{CI} = 3.3 \text{V}, T_A = 25^{\circ}\text{C})$

t_{evcle} Clock Cycle Time100 t_{AS} Address Setup Time15 t_{AH} Address Hold Time15 t_{CSS} Chip Select Setup Time20 t_{CSH} Chip Select Hold Time10 t_{DSW} Write Data Setup Time15 t_{DHW} Write Data Hold Time15 t_{CIKL} Clock Low Time20	Unit
t_{AH} Address Hold Time15 t_{CSS} Chip Select Setup Time20 t_{CSH} Chip Select Hold Time10 t_{DSW} Write Data Setup Time15 t_{DHW} Write Data Hold Time15 t_{CLKL} Clock Low Time20	ns
t_{CSS}Chip Select Setup Time20- t_{CSH} Chip Select Hold Time10 t_{DSW} Write Data Setup Time15 t_{DHW} Write Data Hold Time15 t_{CLKL} Clock Low Time20	ns
t_{CSH} Chip Select Hold Time10 t_{DSW} Write Data Setup Time15 t_{DHW} Write Data Hold Time15 t_{CLKL} Clock Low Time20	ns
t_{CSH} Chip Select Hold Time10 t_{DSW} Write Data Setup Time15 t_{DHW} Write Data Hold Time15 t_{CLKL} Clock Low Time20	ns
t _{DHW} Write Data Hold Time 15 - - t _{CLKL} Clock Low Time 20 - -	ns
t _{CLKL} Clock Low Time 20	ns
	ns
	ns
t _{CLKH} Clock High Time 20	ns
t _R Rise Time 15	ns
t _F Fall Time 15	ns



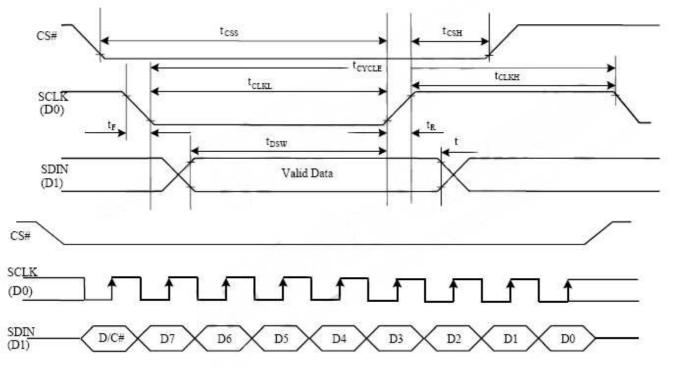


Serial Interface (3-wire SPI)

$(V_{DD} - V_{SS} = 2.4 \text{ to } 2.6 \text{V}, V_{DDIO} = 1.6 \text{V}, V_{CI} = 3.3 \text{V}, T_A = 25^{\circ}\text{C})$

Symbol	Parameter	Min	Typ	Max	Unit
t _{cycle}	Clock Cycle Time	100		8 er 1	ns
t _{AS}	Address Setup Time	15			ns
tAH	Address Hold Time	15	90 197	8	ns
tess	Chip Select Setup Time	20			ns
tCSH	Chip Select Hold Time	10		8 e - 1	ns
tDSW	Write Data Setup Time	15	90 197	8	ns
tDHW	Write Data Hold Time	15			ns
tCLKL	Clock Low Time	20		8 e - 1	ns
tCLKH	Clock High Time	20		8	ns
tR	Rise Time	50 - F		15	ns
tF	Fall Time	-	-	15	ns

Serial interface characteristics (3-wire SPI)



9.2 Display Control Instruction

(D/C#=0, R/W#(WR#) = 0, E(RD#)=1) unless specific setting is stated)

D/C≓	Hex	D7	Dó	D5	D4	D3	D2	D2	D0	Command	Description
0	00	0	0	0	0	0	0	0	0	Enable Gray Scale table	This command is sent to enable the Gray Scale table setting (command B8h)
0	15	0	0	0	1	0	1	0	1	Ĩ.	Set Column start and end address
1	A[6:0]	*	As	As	A ₄	A ₁	A ₂	A	A ₀		A[6:0]: Start Address. [reset=0]
1	B[6:0]	*	Bé	B _s	B.	B ₁	B ₂	B	Bo		B[6:0]: End Address. [rese≔119]
	1923					1	2				Range from 0 to 119
0	5C	0	1	0	1	1	1	0	0	Write RAM Command	Enable MCU to write Data into RAM
0	5D	0	1	0	1	1	1	0	1	Read RAM Command	Enable MCU to read Data from RAM
0	75	0	1	1	1	0	1	0	1		Set Row start and end address
1	A[6:0]	٠	A ₆	A_5	A,	A ₃	A_2	A,	A _a		A[6:0]: Start Address. [reset=0]
1	B[6:0]	•	B ₆	Bs	Bé	B ₁	B ₂	Bi	B ₀	A DED BASE	B[6:0]: End Address. [rese≔127] Range from 0 to 127
0	A0	1	0	1	0	0	0	0	0	(A[0]=0b, Horizontal address increment [reset]
1	A[7:0]	0	0	As	A	0	A	A	A		A[0]=1b, Vertical address increment
1	B[4]	ŝ.		0	B,	0	0	0	1		
25	510001			6400	355	380.8	48	(4)	320		A[1]=0b, Disable Column Address Re-map [reset] A[1]=1b, Enable Column Address Re-map
								- 53			A[1]=10, Elistie Coltanii Address Re-insp
								1.			A[2]=0b, Disable Nibble Re-map [reset] A[2]=1b, Enable Nibble Re-map
										Set Re-map and	
										Dual COM Line mode	A[5]=0b, Disable COM Split Odd Even [reset] A[5]=1b, Enable COM Split Odd Even
										0	B[4], Enable / disable Dual COM Line mode
											00b, Disable Dual COM mode [reset]
											01b, Enable Dual COM mode (MUX \leq 63)
											Note
											⁽¹⁾ COM Split Odd Even mode must be disabled (A[5]=0b) when enabling the Dual COM mode (B[4]=1b)
											Details refer to Section 10.1.6
0	Al	1	0	1	0	0	0	0	1	a	
1	A[6:0]		As	As	A,	A ₃	A ₂	A	A ₀		Set display RAM display start line register from 0-127 Display start line register is reset to 00h after RESET
125	- 10 1 94 (11 12 4)	1	100123	129-22	10000	20,00	19320	eesan i	255	Start Little	Display start the register is reset to 001 after AESE1

D/C#	Hex	D7	D6	D5	D4	D3	D2	D2	D0	Command	Description
0	A2	1	0	1	0	0	0	1	0	Set Display	Set vertical scroll by COM from 0-127
1	A[6:0]	*	A ₆	A ₅	A4	A ₃	A ₂	A	A ₀	Offset	The value is reset to 00H after RESET
0	A4~A7	1	0	1	0	0	X2	X_1	X ₀		A4h = Entire Display OFF, all pixels turns OFF in GS level
											A5h = Entire Display ON, all pixels turns ON in GS level 1
										Set Display Mode	A6h = Normal Display [reset]
										Iviode	
											A7h = Inverse Display (GS0 \rightarrow GS15, GS1 \rightarrow GS14, GS2 \rightarrow GS13,)
0	A8	1	0	1	0	1	0	0	0		This command turns ON partial mode. The partial mode
1	A[6:0]	0	A_6	A5	A4	A_3	A_2	$\mathbf{A}_{\mathbf{l}}$	A_0	Enable Partial	display area is defined by the following two parameters,
1	B[6:0]	0	B ₆	B ₅	B4	B ₃	B ₂	B	B ₀	Display	A[6:0]: Address of start row in the display area
										10 A 8 10 A	B[6:0]: Address of end row in the display area, where B[6:0] must be ≥ A[6:0]
0	A9	1	0	1	0	1	0	0	1	Exit Partial Display	This command is sent to exit the Partial Display mode
0	AB	1	0	1	0	1	0	1	1	1049.0	
1	A[0]	0	0	0	0	0	0	0	A ₀	Function Selection	A[0]=0b, Select external V _{DD} A[0]=1b, Enable internal V _{DO} regulator [reset]
0	AE~AF	1	0	1	0	1	1	1	X ₀		
									1 î	ON/OFF	AEh = Sleep mode ON (Display OFF) AFh = Sleep mode OFF (Display ON)
0	Bl	1	0	1	1	0	0	0	1		A[3:0] Phase 1 period (reset phase length) of 5~31 DCLK
1	A[7:0]	A7	A ₆	As	A4	A_3	A_2	A_1	A ₀		clocks as follow:
											A[3:0] Phase I period
											0000 invalid 0001 invalid
											0010 5 DCLKs
											0011 7 DCLKs
											0100 9 DCLKs [reset]
											1111 31 DCLKs
										Set Phase	A[7:4] Phase 2 period (first pre-charge phase length) of
										Length	3~15 DCLK(s) clocks as follow:
											A[7:4] Phase 2 period
											0000 invalid
											0001 invalid
											0010 invalid
											0011 3 DCLKs
											0111 7 DCLKs [reset]
											: : 1111 15 DCLKs
											1111 17 DCLKS

/C#	Hex	D7	D6	D5	D4	D3	D2	D2	D0	Command	Description	
0	B 3	1	0	1	1	0	0	1	1		A[3:0] [reset=0], divide by DIVSET where	
1	A[7:0]	A7	A ₆	A.	A4	A ₃	A_2	A ₁	A			
	7.5622.54	10.00	1.111	-124		2.985		10094			A[3:0] DIVSET	
											0000 divide by 1	
											0001 divide by 2	
											0010 divide by 4	
											0011 divide by 8	
										Set Front Clock	0100 divide by 16	
										Divider /	0101 divide by 32	
										Oscillator	0110 divide by 64	
										Frequency	0111 divide by 128	
											1000 divide by 256	
											1001 divide by 512 1010 divide by 1024	
											>=1010 divide by 1024	
											>=1011 mvand	
											A[7:4] Oscillator frequency, frequency increases as lev increases [reset=1100b]	
0	B4	1	0	1	1	0	1	0	0		A[1:0] = 00b: Enable external VSL	
1	A[1:0]	1	0	1	0	0	0	A_1	Ao		A[1:0] = 10b: Internal VSL [reset]	
1	B[7:3]	B7	B ₆	B ₅	B4	B3	1	0	1	Display Enhancement A	B[7:3] = 11111b: Enhanced low GS display quality B[7:3] = 10110b: Normal [reset]	
0	B5	1	0	1	1	0	1	0	1		A[1:0] GPIO0: 00 pin HiZ, Input disabled	
1	A[3:0]	*	*	*	8	Α,	A ₂	A	A		01 pin HiZ, Input enabled	
÷	A[J.V]	- 23	49	- 28	2	- 22	~2	~1	~		10 pin output LOW [reset] 11 pin output HIGH	
										Set GPIO		
										Control on 1152 266	A[3:2] GPIO1: 00 pin HiZ, Input disabled 01 pin HiZ, Input enabled 10 pin output LOW [reset]	
								-			11 pin output HIGH	
					8 1	5 5		6	2	0		
0	B6	1	0	1	1	0	1	1	0		A[3:0] Second Pre-charge period	
1	A[3:0]	*	*	*	8	A ₃	A ₂	A	A ₀	and the second se	0000b 0 delk	
÷.	[0]	- 28	49	- 23)	24	- 33	202			Set Second	0001b 1 delk	
										Precharge	FINE STREET, ST	
										Period	1000b 8 dclks [reset]	
	I										1111b 15 delks	
		L - 3	0	1	1	1	0	0	0		The next 15 data bytes define Gray Scale (GS) Table by	
0	B8	1	1.004.01	44	Al.	Al ₁	Al,	Al_1	Al_{ij}	8	setting the gray scale pulse width in unit of DCLK's	
0 1	B8 A1[7:0]		Al ₆	Al,	10000	1000	A2,	A2,	A20		(ranges from 0d ~ 180d)	
		Al,	100000	A1 ₃ A2 ₅	A2.	A2,	2775					
1	A1[7:0]	Al,	100000	242600	A2,	A2,		25	135	Set Grav Scale	A1(7-0): Commo Sotting for CS1	
1 1	A1[7:0]	Al, A2,	100000	A25	222	18285	.	2495		Set Gray Scale Table	A1[7:0]: Gamma Setting for GS1, A2[7:0]: Gamma Setting for GS2	
1 1 1	A1[7:0] A2[7:0]	Al, A2,	100000	A25	120	1000		11 12 12 12 12 12 12 12 12 12 12 12 12 1		Set Gray Scale Table	A1[7:0]: Gamma Setting for GS1, A2[7:0]: Gamma Setting for GS2,	
1 1 1 1	A1[7:0] A2[7:0]	Al, A2,	A2,	A25	1.1.1	san an ang	ga n ag	14 F	44 - 15 - 16 - 16 - 16 - 16 - 16 - 16 - 16	Set Gray Scale Table		
1 1 1 1	A1[7:0] A2[7:0]	Al, A2, Al4,	A2 ₅	A25	A14,	- A14,	A142	Al4ı		Set Gray Scale Table	A2[7:0]: Gamma Setting for GS2,	

D/C# D7 D6 D5 D4 D3 D2 D2 D0 Hex Command Description Note ⁽¹⁾ 0 ≤ Setting of GS1 < Setting of GS2 < Setting of GS3.....</p> < Setting of GS14 < Setting of GS15 Refer to Section 8.8 for details ⁽²⁾ The setting must be followed by the Enable Gray Scale Table command (00h) The default Linear Gray Scale table is set in unit of DCLK's 0 **B**9 1 0 1 1 1 0 0 1 as follow GS0 level pulse width = 0; GS1 level pulse width = 0; GS2 level pulse width = 8; GS3 level pulse width = 16; Select Default Linear Gray Scale table GS14 level pulse width = 104; GS15 level pulse width = 112 Refer to Section 8.8 for details Set pre-charge voltage level [reset = 17h] BB 0 1 0 1 1 1 0 1 1 1 A[4:0] * * * A4 A., A_2 A₁ A_0 Hex code A[5:1] pre-charge voltage Set Pre-charge 00000 00h 0.20 x Vcc voltage 11111 3Eh 0.60 x Vcc Set COM deselect voltage level [reset = 04h] 0 BE 1 0 1 1 1 1 1 0 A[3:0] =1 A[3:0] * * 3 A₃ A_2 A_l A₀ A[2:0] Hex code V COME 0.72 x Vo 0000 00h Set VOOLH 0100 04h 0.80 x Vcc 0111 07h 0.86 x Vcc 0 C1 1 1 0 0 0 0 0 1 A[7:0]: Contrast current value, range:00h~FFh, Set Contrast i.e. 256 steps for ISEO current [reset = 7Fh] A_2 A₁ 1 A[7:0] A7 A_o As A₅ A4 A₃ Current A[3:0] = 0 1 0 C7 1 1 0 0 1 1 0000b, reduce output currents for all colors to 1/16 A_3 1 A[3:0] * * * 8 A_2 A A_0 0001b, reduce output currents for all colors to 2/16 Master Contrast Current Control 1110b, reduce output currents for all colors to 15/16 1111b, no change [reset] A[6:0]: Set MUX ratio from 16MUX ~ 128MUX 0 CA 1 1 0 0 1 0 1 0

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1

A[6:0]

* A6

As

 A_4

A₃ A₂

 A_1

 A_0

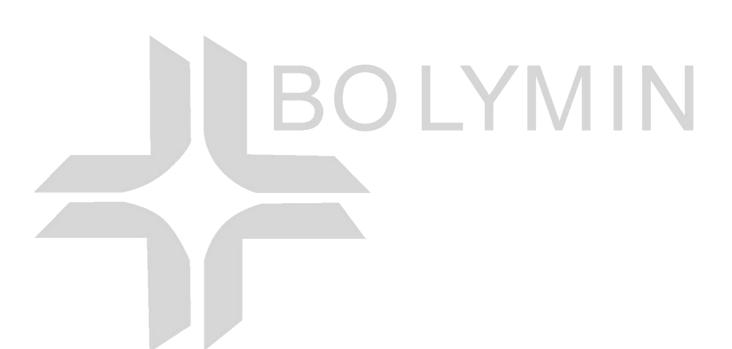
Set MUX Ratio A[6:0] = 15d represents 16MUX

A[6:0] = 127d represents 128MUX [reset]

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D/C#	Hex	D 7	D6	D5	D4	D3	D2	D2	D 0	Command	Description
0 1 1	D1 A[5:4] 20	1 1 0	1 0 0	0 As 1	1 A4 0	0 0 0	0 0 0	0 1 0	1 0 0		A[5:4] = 00b: Reserved A[5:4] = 10b: Normal [reset]
0	FD A[2]	1 0	1 0	1 0	1 1	1 0	1 A2	0	1 0	Set Command Lock	A[2]: MCU protection status [reset = 12h] A[2] = 0b, Unlock OLED driver IC MCU interface from entering command [reset] A[2] = 1b, Lock OLED driver IC MCU interface from entering command Note ⁽¹⁾ The locked OLED driver IC MCU interface prohibits all commands and memory access except the FDh command

Note (1) "*" stands for "Don't care".



9.3 Power ON / OFF Sequence & Application Circuit

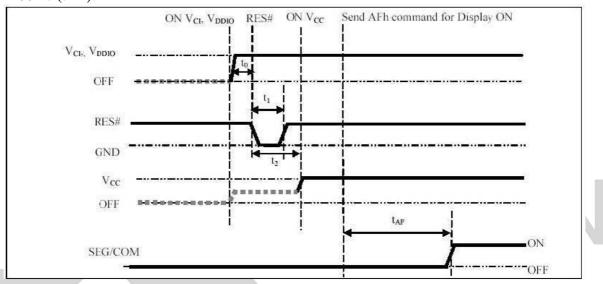
POWER ON / OFF SEQUENCE

Power ON sequence:

- 1. Power ON VDD
- 2. After VDD become stable, set wait time at least 1ms (t0) for internal VDD become stable. Then set RES# pin LOW (logic low) for at least 100us (t1) (4) and then HIGH (logic high).

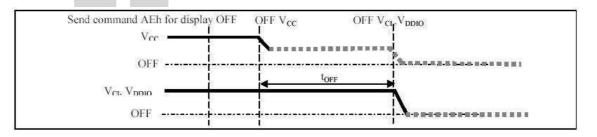
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- 3. After set RES# pin LOW (logic low), wait for at least 100us (t2). Then Power ON VCC.(1) 4. After VCC become stable, send command AFh for display ON. SEG/COM will be ON after
 - 200ms (tAF).



Power OFF sequence:

- 1. Send command AEh for display OFF.
- 2. Power OFF VCC.(1), (2)
- 3.Wait for tOFF. Power OFF VCI, VDDIO. (where Minimum tOFF=80ms (3), Typical tOFF=100ms)



Note:

- (1) Since an ESD protection circuit is connected between VCI, VDDIO and VCC, VCC becomes lower than VCI whenever VCI, VDDIO is ON and VCC is OFF as shown in the dotted line of VCC.
- (2) VCC should be kept float (disable) when it is OFF.
- (3) VCI, VDDIO should not be Power OFF before VCC Power OFF.
- (4) The register values are reset after t1.
- (5) Power pins (VCI, VCC) can never be pulled to ground under any circumstance.

10 Quality Assurance

10.1 Inspection conditions

1. The inspection and meaurement are performed under the following conditions,

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- 2. unless otherwise specified.
- 3. Temperature: 25±5℃
- 4. Humidity: 50±10%R.H.
- 5. Distance between the panel and eyes of the inspector \geq 30cm

10.2 Inspection Parameters

	Severity	Inspection Item	Defect	Remark		
			(1) Non-displaying			
		1. Panel	(2) Line defects			
			(3) Malfunction			
	Major	ь.	(4) Glass cracked			
	Defect	2. Film	(1) Film dimension out of	Can not be		
		2.1 1111	specification	assembled		
		3. Dimension	(1) Outline dimension out			
		5. Dimension	of specification			
			(1) Glass scratch			
		1. Panel	(2) Glass cutting NG			
			(3) Glass chip			
			(1) Polarizer scratch			
	Minor	2. Polarizer	(2) Stains on surface	Appearance		
	Defect		(3) Polarizer bubbles	defect		
			(1) Dim spot 、	ueleci		
		3. Displaying	Bright spot 🔻 dust			
		4. Film	(1) Damage			
		4. [1]	(2) Foreign material			

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	Description		Criterion		AQL	
	1. Glass scratch	Width (mm) W≤0.03 0.03<	Length (mm) L Ignore L≦3 	number of pieces permitted Ignore 3 None Ignore	Minor	
	2. Polarizer bubble	$\begin{array}{c} \text{Size} \\ \Phi \leqq 0.2 \\ 0.2 < \Phi \leqq 0.5 \\ 0.5 < \Phi \\ \text{beyond A.A.} \end{array}$	number pieces per Ignor 2 0 Ignor	<u>mitted</u> e	Minor	
	3. Dimming spot 、 Lighting spot 、 Dust	average $D \leq 0.1$ $0.1 < D \leq 0.15$ $0.1 < D \leq 0.2$ $0.15 < D \leq 0.2$ $0.2 < D$ beyond A.A. D =(long diametePixel off is not allowed by the second sec	2 1 0 Ignor	e	Minor	

10.3 WARRANTY POLICY

Bolymin . Will provide one-year warranty for the products only if under specification operating conditions.

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If there are functional defects found during the period of warranty, the defective products would be replaced on a one-to-one basis.

Bolymin would not be responsible for any direct/indirect liabilities consequential to any parties.

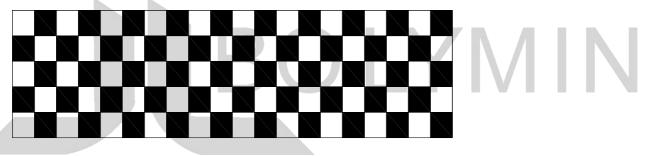
10.4 MTBF

10.4.1 .MTBF based on specific test condition is 13K hours.

10.4.2 Test Condition:

10.4.2.1 Supply Voltage: Vcc=14V

- 10.4.2.2 Luminance: 80cd/m2
- 10.4.2.3 Operation temperature and humidity: 25 $\,^\circ\!\mathbb{C}\,$ and 50%RH
- 10.4.2.4 Run-Patterns:



10.4.3 Test Criteria:

Luminace has decayed to less than 50% of the initial measured luminance.



11.Reliability ■Content of Reliability Test

NO.	Items.	Specification	Applicable Standard
1	High temp. (Non-operation)	85℃, 240hrs	
2	High temp. (Operation)	70℃, 120hrs	
3	Low temp. (Operation)	-40℃, 120hrs	
4	High temp. / High. humidity (Operation)	65℃, 90%RH, 120hrs	
5	Thermal shock(Non-operation)	-40℃ ~85℃ (-40℃ /30min; transit /3min; 85℃ /30min; transit /3min) 1cycle: 66min, 100 cycles.	
6	Vibration	Frequency : 5~50HZ, 0.5G Scan rate : 1 oct/min Time : 2 hrs/axis Test axis : X, Y, Z	_

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for item 1 & 4 & 5.

Criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: >50% of initial value.
- 4. Current consumption : within ±50% of initial value.

Reliability Test

Bolymin only guarantees the reliability of the panel under the test conditions and durations listed in the specification, and is not responsible for any test results that are conducted using more stringent conditions and/or with lengthened durations. Also, when the testing the panel in a chamber or oven, make sure they won't produce any condensation on the panel, especially on the electrical leads, before lighting on the panel to see if it passes the test. Also the panel should rest for about an hour at room temperature and pressure before the measurement, as indicated in the specification. Be aware that one should use fresh panel for each of the reliability test items listed in the specification, in other words, don't use the panels that were tested for subsequent tests.

12.Precautions for Handling

- 12.1 When handling the module, wear powder-free antistatic rubber finger cots, and be careful not to bend and twist it.
- 12.2 The OLED module is consisted of glass and film, and it should avoid pressure, strong impact, or being dropped from a height.

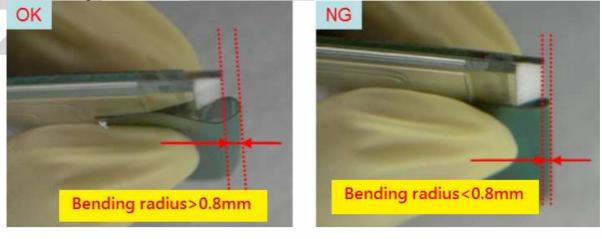
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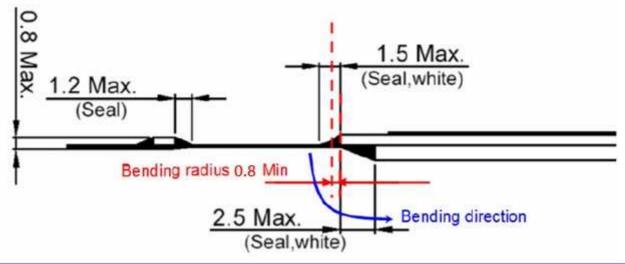
12.3 The OLED module is an electronic component and is subject to damage caused by Electro Static

Discharge (ESD) and hence normal ESD precautions must be taken when handling it. Also, appropriate ESD protective environment must be administered and maintained in the production line. When handling and assembling the panel, wear an antistatic wrist strap with the alligator clip attached to the ground to prevent ESD damage on the panel. Also, ground the tools being used for panel assembly and make sure the working environment is not too dry to cause ESD problems. (See the photos below).



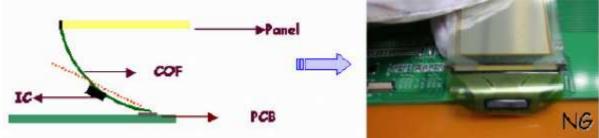
12.4 Please do not bend the film near the substrate glass.(this could cause film peeling and COF damage) and the peeling strength about 600g/cm, the bending <20times and the bending radius :R>0.8mm



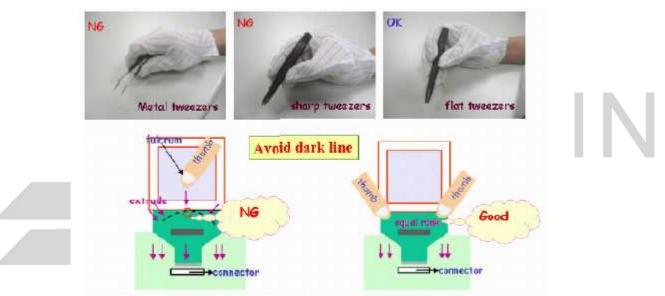




12.5 Avoid bending the film at IC bonding area.(>1.5mm)(this could damage the ILB bonding)



12.6 Use both thumbs to insert COF into the connector when assembling the panel. See the photo on the far right below for correct insertion of the film into the connector (one-handed insertion exerts uneven force on the film and could cause its breakage, photo on the left)



12.7 Do not wipe the pin of film with the dry or hard materials that will damage the surface. When cleaning the display surface, use soft cloth solvent and wipe gently (Recommend solvent: IPA, alcohol), and do not wipe the display with dry or hard materials that will damage the polarizer surface and do not use the solvent like: Water, Acetone, Aromatic



13. Precautions for Electrical

13.1. Design using the settings in the specification

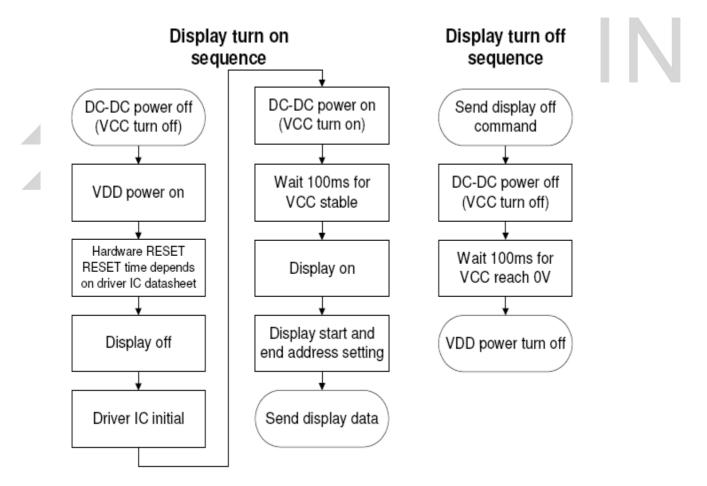
It is extremely important to design and operate the panel using the settings listed in the specification. This includes voltage, current, frame rate, duty cycle... etc. Operation of the OLED outside the specified range in the specification should be entirely avoided to ensure proper operation of the OLED.

13.2. Maximum Ratings

To ensure proper operation of the panel, never design the panel with parameters running over the maximum ratings listed in the specification. Also the logic voltages such as VIL and VIH have to be within the specified range in the specification to prevent any improper operation of the panel.

13.3 Power on/off procedure

Any operation that does not comply with the procedure could cause permanent damage of the IC and should be avoided. When the logic power is not on, do not activate any input signal. Abrupt shutdown of power to the module, while the OLED panel is on, could cause OLED panel malfunctioning.



13.4 Power savings

To save power consumption of the OLED, one can use partial display or sleep mode when the panel is not fully activated. Also, if possible, make maximum use of black background to save power. The OLED is a self-luminous device, and a particular pixel cluster or image can be lit on via software control, so power savings can be achieved by partial display or dimming down the luminance. Depending on the application, the user can choose among Ultra Bright Mode, Normal Operation Mode, and Sleeping Mode.

The power consumption is almost in direct proportion to the brightness of the panel, and also

in direct proportion to the number of pixels lit on the panel, so the customer can save the power by the use of black background and Sleeping Mode. One benefit from using these design schemes is the extension of the OLED lifetime.

13.5 Residual Image (Image Sticking)

The OLED is a self-emissive device. As with other self-emissive device or displays consisting of self-emissive pixels, when a static image frozen for a long period of time is changed to another one with all-pixels-on background, residual image or image sticking is noticed by the human eye. Image sticking is due to the luminance difference or contrast between the pixels that were previously turned on and the pixels that are newly turned on. The time when image sticking happens depends on the luminance decay curve of the display. The slower the decay, the less prominent the image sticking is. It is strongly recommended that the user employ the following three strategies to minimize image sticking

- 13.5.1Employ image scrolling or animation to even out the lit-on time of each and every pixel on the display, also could use sleeping mode for reduced the residual image and extend the power capacity.
- 13.5.2Minimize the use of all-pixels-on or full white background in their application because when the panel is turned on full white, the image sticking from previously shown patterns is the most revealing. Black background is the best for power savings, greatest visibility, eye appealing, and dazzling displays
- 13.5.3If in the reliability test when a static logo is used, change the pattern into its inverse (i.e., turn off the while pixels and turn on the previously unlit pixels) and freeze the inverse pattern as long as the original logo is used, so every pixel on the panel can be lit on for about the same time to minimize image sticking, caused by the differential turn-on time between the original and its reverse patterns

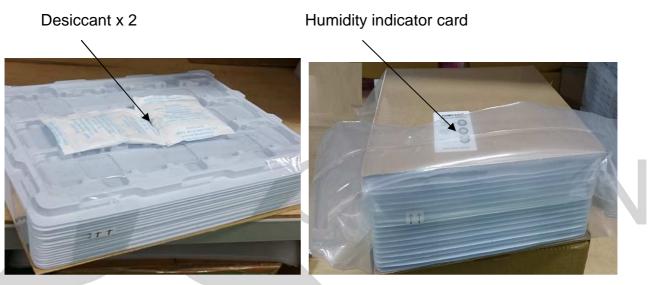


14. Precautions for Storage

Although the storage conditions and guarantee period are indicated in the specification, it is advisable to store the packed cartons or packages at $23^{\circ}C \pm 5^{\circ}C$,55% ±10% RH(Note A), Do not store the OLED module under direct sunlight or UV light and for best panel performance. The constant working OLED display module decays slower than the module that is not working. And it's better to use the module on the field within one month after unpacking the package.

Note (A):

Vacuum Packaging



Humidity indicator card

As the humidity increases, the chemically impregnated spots change from a brown color (DRY) to a blue color (HUMID).

